

ABSTRACT OF THE DISCLOSURE

Stacked metal sections serve as two leads of an IC package. In one embodiment, an IC chip is mounted on one section serving as the terminal for the bottom electrode of the chip, and the top electrode of the chip is wire-bonded to the other section serving as another terminal for the chip. The thin sheet metal permits narrower etched separation between the two metal sections. Stacking of two pre-etched thin sheet metals strengthens the substrate. The package is covered with glue to hold the two sections together. The stacked pre-etched metal sheets can serve as a common substrate for a matrix of IC packages, which can later be cut in two orthogonal directions to yield individual packages.

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